



5-TVS/ZENER ARRAY FOR ESD AND LATCH-UP PROTECTION

This 5-TVS/Zener Array has been designed to Protect Sensitive Equipment against ESD and to prevent Latch-Up events in CMOS circuitry, operating at 3.3V and 5V, as well available for 12V, 15V, and 24V Systems. This TVS array offers an integrated solution to protect up to 5 data lines where the board space is a premium.

SPECIFICATION FEATURES

- 100W Power Dissipation (8/20µs Waveform)
- Low Leakage Current
- Very Low Clamping Voltage
- IEC61000-4-2 ESD 20kV air, 15kV Contact Compliance
- Operating voltage options for 3.3V, 5V, 12V, 15V, and 24V
- Industry Standard SOT363 (SC70-6L) Package

APPLICATIONS

- Personal Digital Assistant (PDA)
- SIM Card Port Protection (Mobile Phone)
- Portable Instrumentation
- Mobile Phones and Accessories
- Memory Card Port Protection

MAXIMUM RATINGS (Per Device)

Rating	Symbol	Value	Units
Peak Pulse Power (8/20µs Waveform)	P _{pp}	100	W
ESD Voltage (HBM)	V _{ESD}	25	kV
Operating Temperature Range	ТJ	-55 to +150	°C
Storage Temperature Range	T _{stg}	-55 to + 150	°C

ELECTRICAL CHARACTERISTICS (Per Device) Tj = 25°C PJSMF03LC

Parameter	Symbol	Conditions	Min	Typical	Max	Units
Reverse Stand-Off Voltage	V _{WRM}				3.3	V
Reverse Breakdown Voltage	V_{BR}	I _{BR} = 10 mA	4.7		5.6	V
Reverse Leakage Current	۱ _R	V _R = 3.3V			250	μA
Clamping Voltage (820µs)	Vc	I _{pp} =5A			7.5	V
Clamping Voltage (8/20µs)	Vc	I _{pp} = 9A			9	V
Off State Junction Capacitance	Cj	0 Vdc Bias f = 1MHz Between I/O pins and pin 2			160	pF
Off State Junction Capacitance	Cj	3.3 Vdc Bias f = 1MHz Between I/O pins and pin 2			90	pF





ELECTRICAL CHARACTERISTICS (Per Device) Tj = 25°C

PJSMF05LC

Parameter	Symbol	Conditions	Min	Typical	Max	Units
Reverse Stand-Off Voltage	V _{WRM}				5	V
Reverse Breakdown Voltage	V _{BR}	I _{BR} =1mA	6.2			V
Reverse Leakage Current	۱ _R	V _R =5V			0.5	μA
Clamping Voltage (8/20µs)	Vc	I _{pp} =5A			10	V
Clamping Voltage (8/20µs)	Vc	I _{pp} = 9A			11	V
Off State Junction Capacitance	Cj	0 Vdc Bias f = 1MHz Between I/O pins and pin 2			100	pF
Off State Junction Capacitance	Cj	5 Vdc Bias f = 1MHz Between I/O pins and pin 2			45	pF

PJSMF12LC

Parameter	Symbol	Conditions	Min	Typical	Max	Units
Reverse Stand-Off Voltage	V _{WRM}				12	V
Reverse Breakdown Voltage	V _{BR}	I _{BR} =1mA	13.3			V
Reverse Leakage Current	I R	V _R =12V			0.5	μA
Clamping Voltage (8/20µs)	Vc	I _{pp} =3A			18	V
Clamping Voltage (8/20µs)	Vc	I _{pp} = 5A			20	V
Off State Junction Capacitance	Cj	0 Vdc Bias f = 1MHz Between I/O pins and pin 2			50	pF

PJSMF15LC

Parameter	Symbol	Conditions	Min	Typical	Max	Units
Reverse Stand-Off Voltage	V _{WRM}				15	V
Reverse Breakdown Voltage	V _{BR}	I _{BR} =1mA	16.6			V
Reverse Leakage Current	l _R	V _R =15V			0.5	μA
Clamping Voltage (8/20µs)	Vc	1 _{pp} = 3A			23	V
Clamping Voltage (8/20µs)	Vc	$I_{pp} = 4A$			25	V
Off State Junction Capacitance	Cj	0 Vdc Bias f = 1MHz Between I/O pins and pin 2			40	pF





ELECTRICAL CHARACTERISTICS (Per Device) Tj = 25°C

PJSMF24LC

Parameter	Symbol	Conditions	Min	Typical	Max	Units
Reverse Stand-Off Voltage	V _{WRM}				24	V
Reverse Breakdown Voltage	V _{BR}	I _{BR} =1mA	26.7			V
Reverse Leakage Current	I _R	V _R =24V			0.5	μΑ
Clamping Voltage (8/20µs)	Vc	I _{pp} =1A			35	V
Clamping Voltage (8/20µs)	Vc	I _{pp} = 2A			45	V
Off State Junction Capacitance	Cj	0 Vdc Bias f = 1MHz Between I/O pins and pin 2			30	pF





TYPICAL CHARACTERISTICS 25°C unless otherwise noted







LAYOUT DIMENSIONS AND SUGGESTED PAD LAYOUT

